

ADVANCED MASK ALIGNER LITHOGRAPHY (AMALITH)

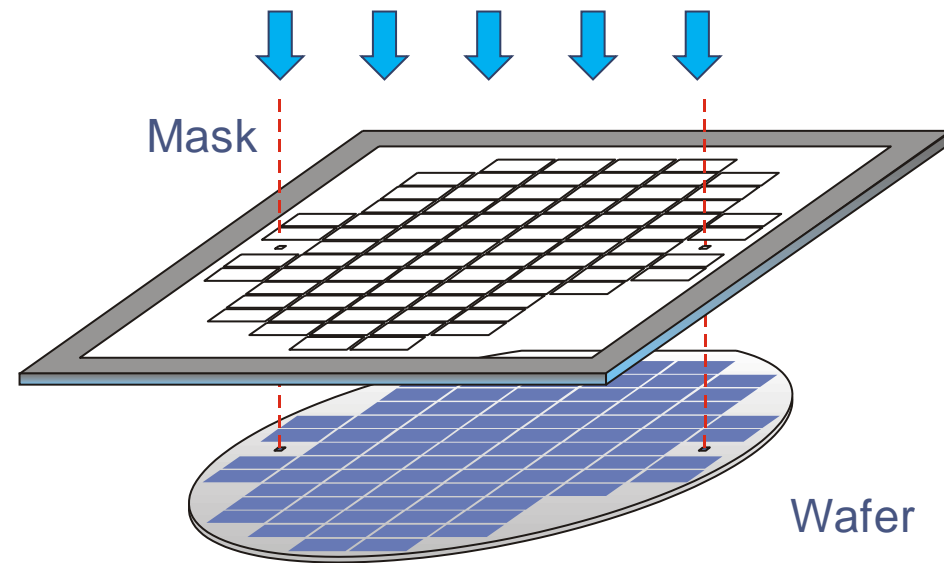
Photolithography Enhancement for SUSS Mask Aligners

SÜSS MicroTec AG, www.suss.com

SUSS MicroOptics SA, www.suss.ch, info@suss.ch

„Shadow Printing“ Lithography

- + Mask illumination using collimated UV light
- + Resolution \leftrightarrow proximity gap



MO EXPOSURE OPTICS®

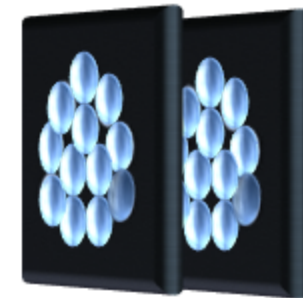
The new Illumination System for all SÜSS Mask Aligners

CONVENTIONAL MASK ALIGNER ILLUMINATION

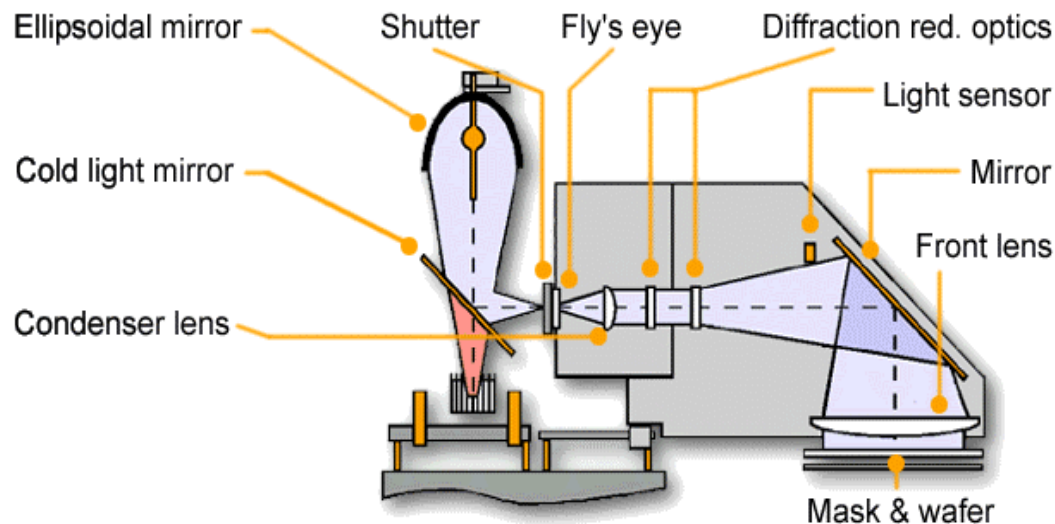
- + Lamp readjustment required
- + Uniformity change over lamp lifetime
- + Daily uniformity test required
- + Variation of illumination light over mask (angular spectrum)



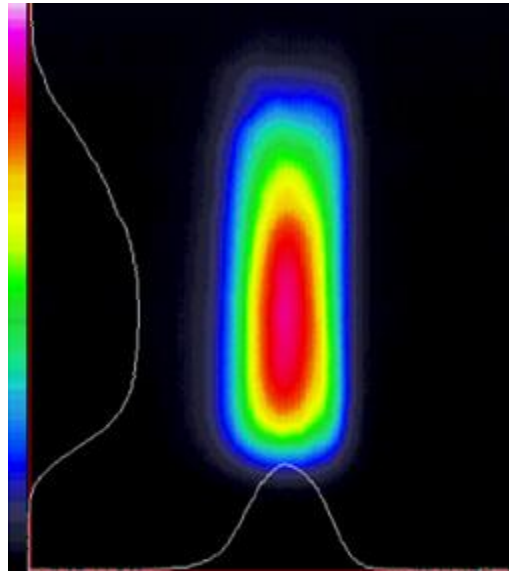
"Fly's Eye"



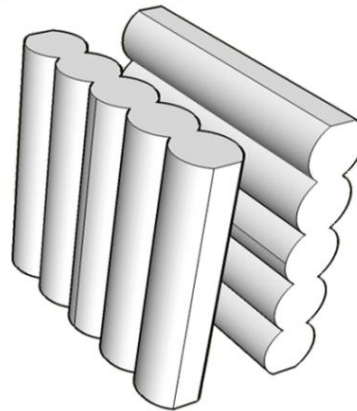
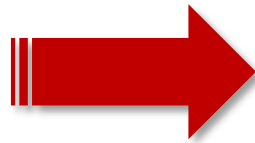
HR or LGO
Lens Plates



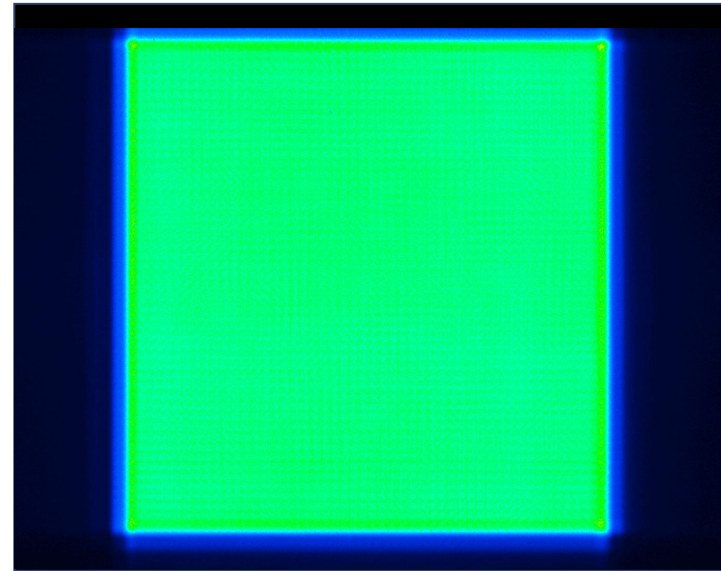
Forgot to control light
uniformity this morning.



Light Source

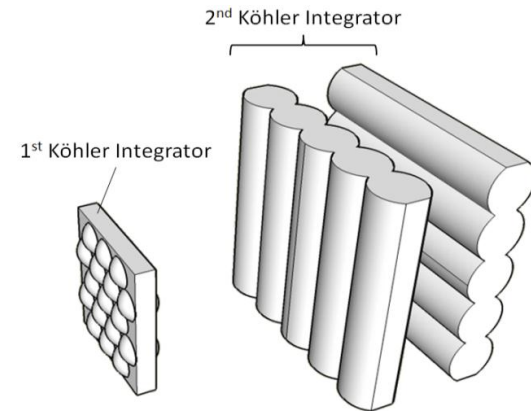


Microlens Optical Integrator

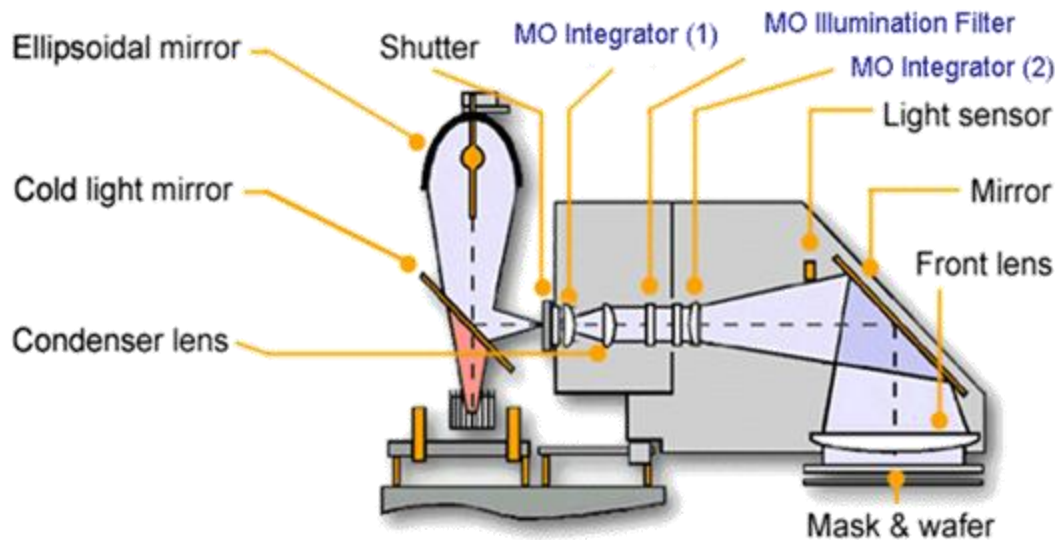


Flat-Top Illumination

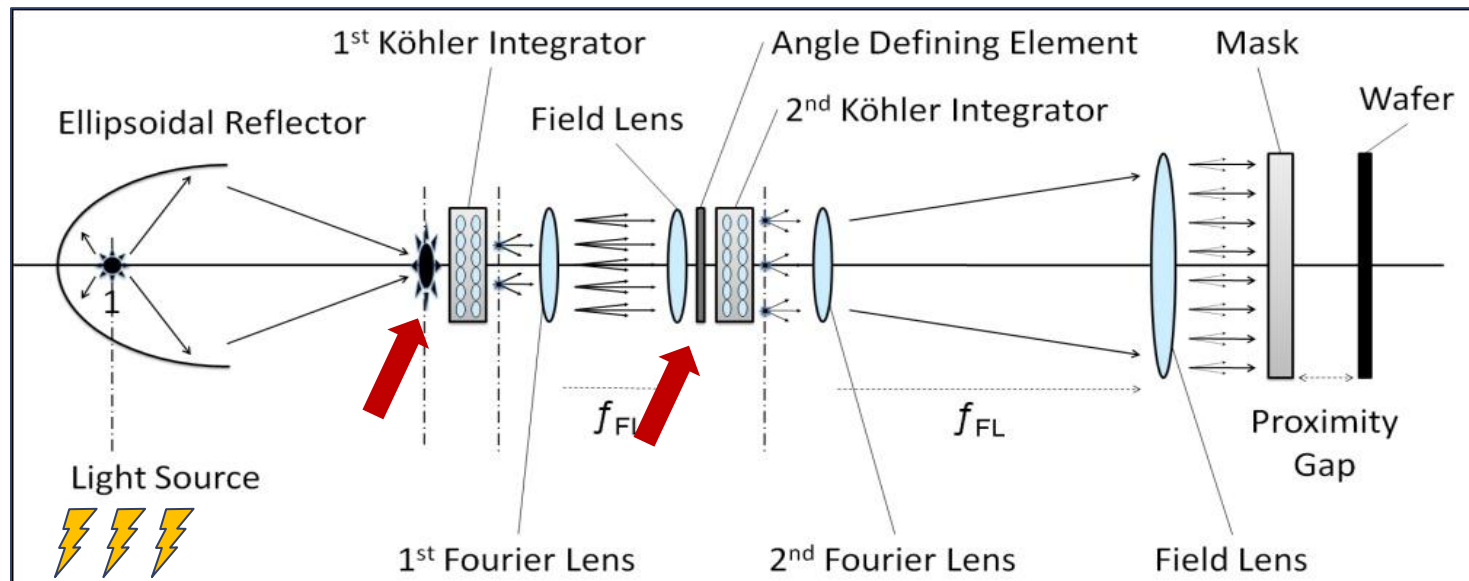
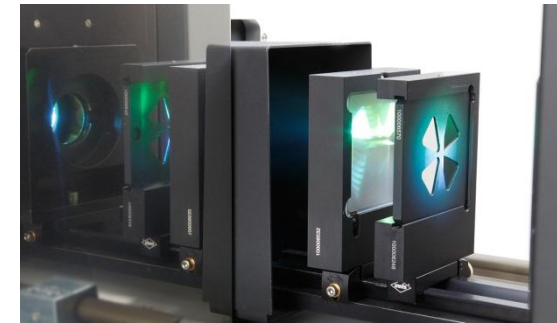
- NO** Lamp readjustment required
- NO** Uniformity change over lamp lifetime
- NO** Daily uniformity test required
- NO** Variation of illumination light over mask (angular spectrum)

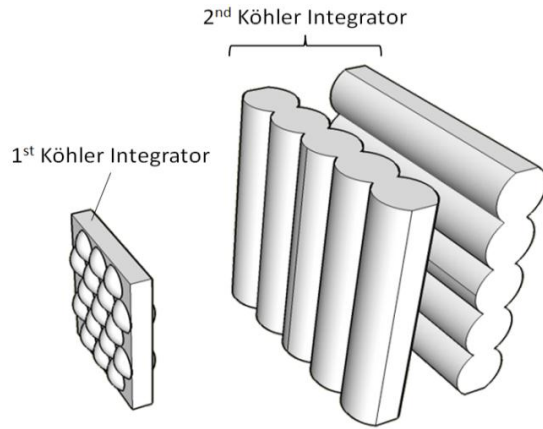


Microlens Optical Integrators

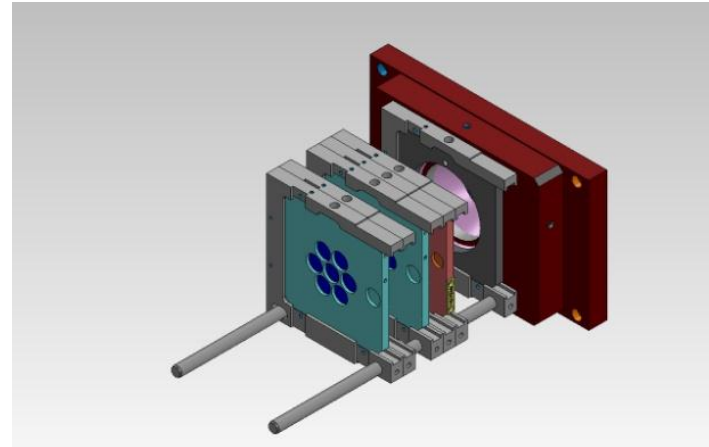


- + 2x Microlens Optical Integrators in the Mask Aligner illumination system
- + Light homogenization in both Fourier planes
- + Self calibrating light source
- + Illumination filter plate (IFP)

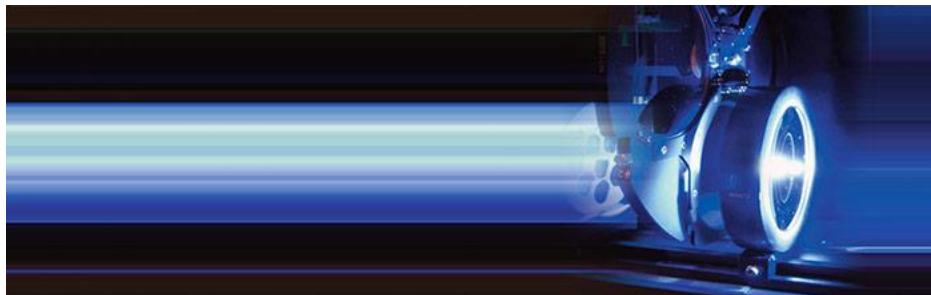




Microlens Optical Integrators



Quick Installation in Mask Aligner



+ Conventional Mask Aligner in Production

- Daily light measurement (9 or 12 points uniformity)
 - ⇒ 5 min x 365 day ~ 30 hours per year
- 12x lamp exchange per year
 - ⇒ 30 min x 10 ~ 6 hours per year
 - ⇒ 36 hours less productive time & labor costs per year

+ MO Exposure Optics®

- No uniformity measurements, no lamp alignment!
- Improved uniformity, telecentric illumination
- CD uniformity improvement = Yield!
- Process stability assurance = Yield!
- Convenience!

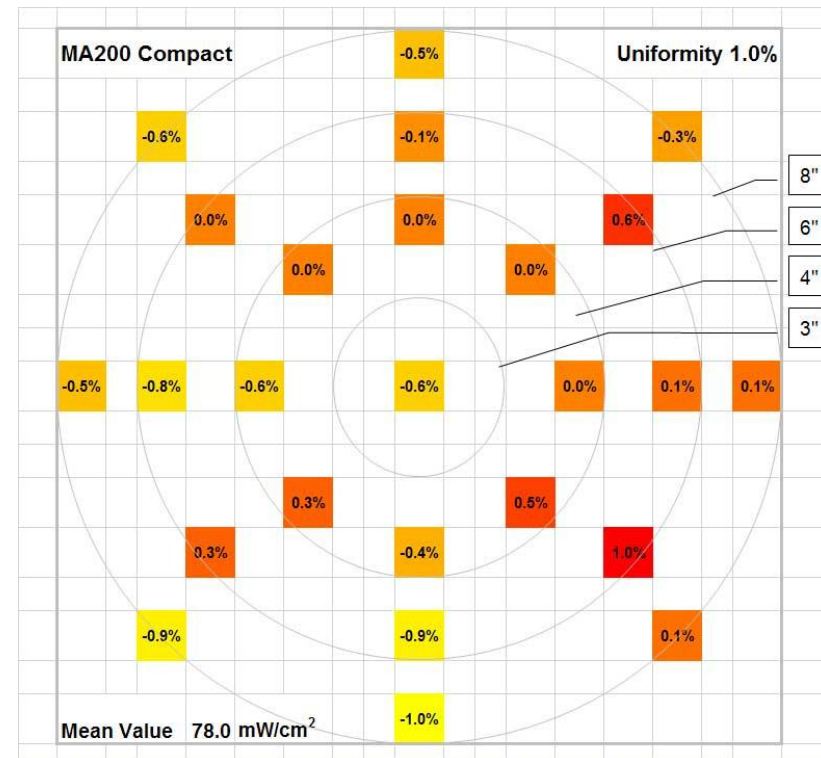


Forgot to control light uniformity this morning.



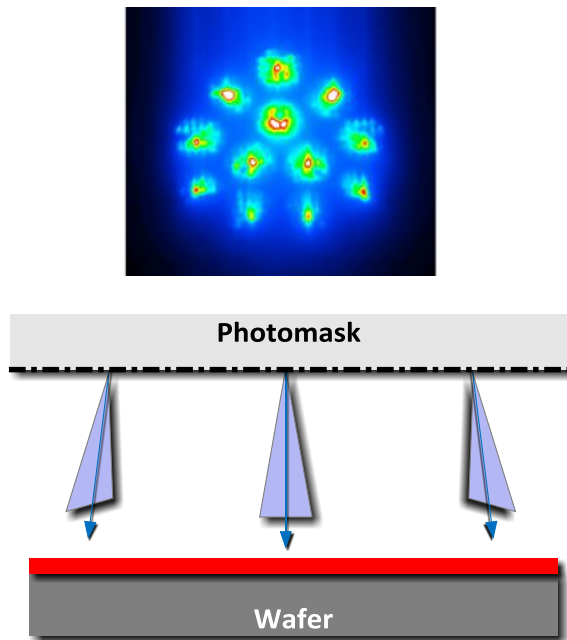
BETTER UNIFORMITY – INDEPENDENT OF LAMP POSITION

- + Excellent light uniformity
- + No lamp misalignment
- + No uniformity change due to degradation of lamp electrode during lifetime cycle

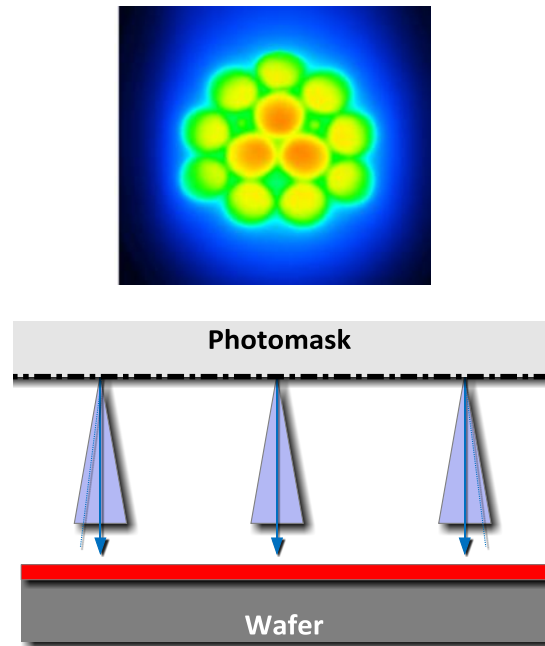


Deviation from mean value in [%] for Ø200mm in MA200 Compact

Conventional



MO Exposure Optics[®]



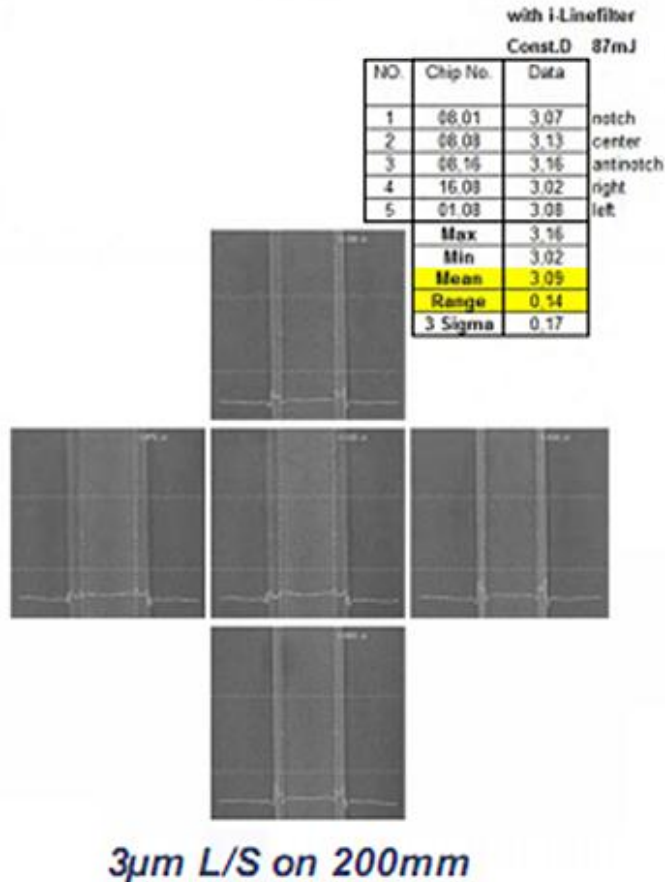
Angular spectrum illumination light

Near-field light distribution behind photomask

Uniform angular distribution over the entire mask plane

INDUSTRY EXAMPLE

CD-UNIFORMITY, 3 μ m LINES AT 30 μ m GAP

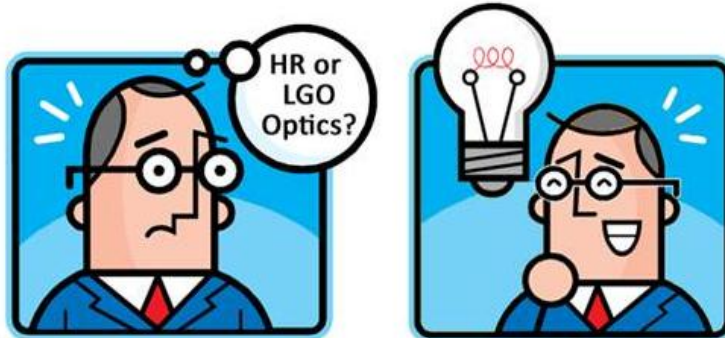


850W	CD										min	max	%+	%-	Dosis
	Front	Center	Back	Right	Left	Range	3sig	MW							
1	3.07	3.13	3.16	3.02	3.08	0.00	0.17	3.09	3.0	3.2	2.5	-2.2	87mJ		
2	3.06	3.15	3.19	3.08	3.09	0.14	0.17	3.12	3.1	3.2	1.8	-2.5	87mJ		
3	3.09	3.06	3.14	3.14	3.07	0.13	0.12	3.10	3.1	3.1	1.3	-1.4	87mJ		
4	3.12	3.10	3.17	3.10	3.12	0.08	0.09	3.12	3.1	3.2	0.8	-1.6	87mJ		
5	3.19	3.20	3.27	3.17	3.14	0.08	0.14	3.20	3.1	3.3	1.8	-2.3	87mJ		
6	3.08	3.06	3.14	3.13	3.02	0.13	0.15	3.09	3.0	3.1	2.2	-1.7	87mJ		
7	3.20	3.16	3.21	3.20	3.18	0.12	0.08	3.19	3.2	3.2	1.3	-0.7	87mJ		
8	3.22	3.11	3.23	3.19	3.13	0.11	0.15	3.18	3.1	3.2	2.0	-1.5	87mJ		
MW	3.13	3.12	3.19	3.13	3.10	0.14	0.10	3.13							
3sigM	0.20	0.14	0.13	0.19	0.15	0.14	0.11	0.14							
									3.1	1.5	%+				
									3.2	-1.9	%-				

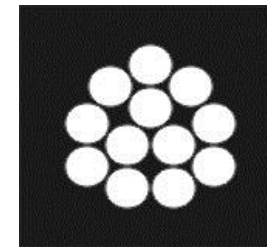
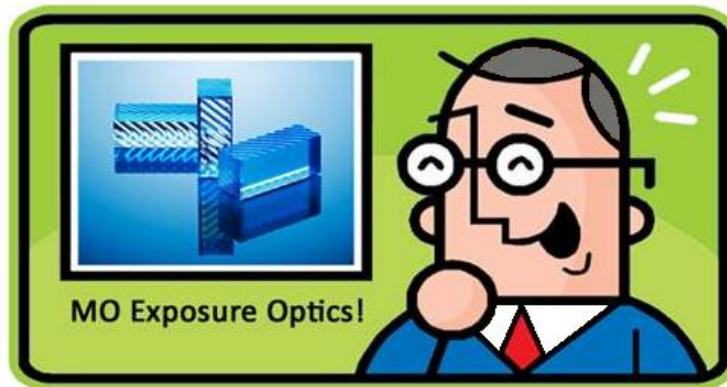
MA200 Compact

MOE(200mm production line in semiconductor fab)

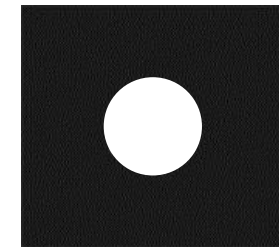
- + 3 μ m lines
- + 30 μ m proximity gap
- + i-line illumination (MO Exposure Optics®)
- + Resist IX335, 1.5 μ m thick
- + 0.17 μ m variation (3 Sigma)



Changeover from
HR-Optics to LGO-Optics
in less than
5 minutes!

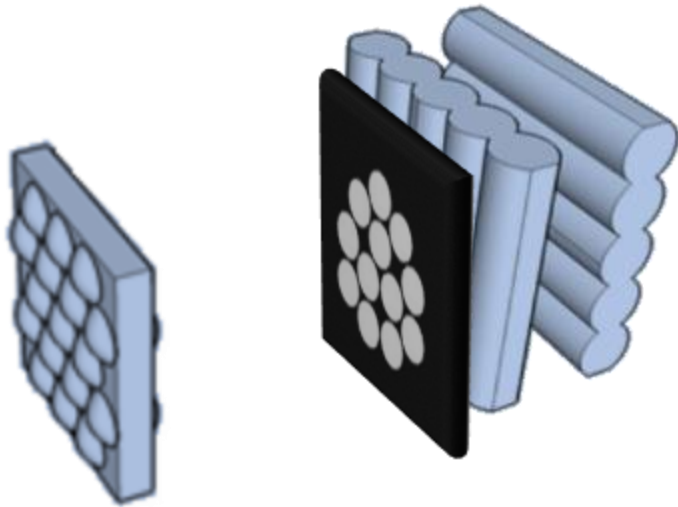


IFP-HR
„High Resolution“

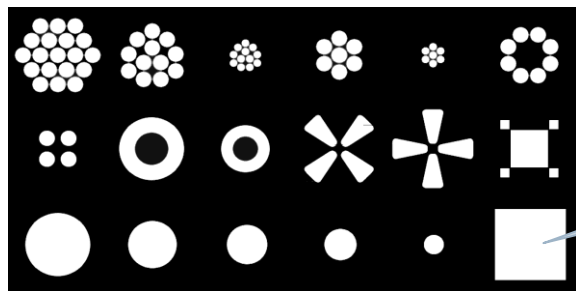
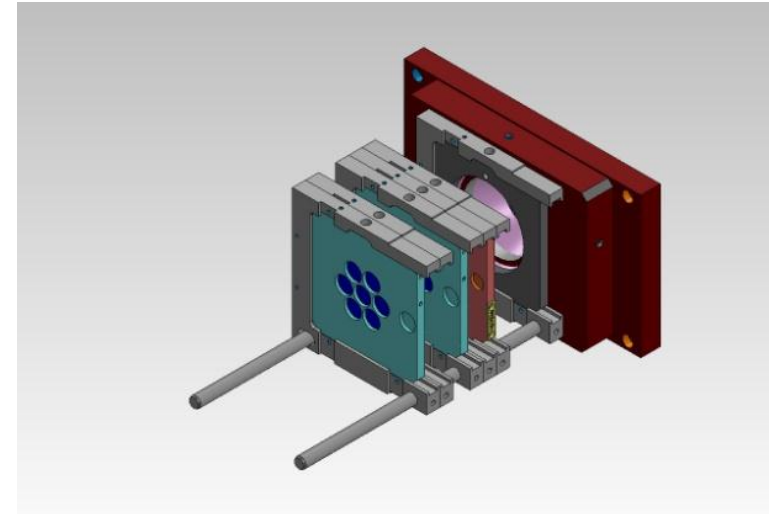


IFP-LGO
„Large Gap“

ILLUMINATION FILTER PLATES (IFP)



IFP HR



Pupil Fill Ratio (PFR) 130%
IFP " More Light"

- + Self calibrating light source - no periodic uniformity measurement
 - + Easy lamp change without lamp adjustment
 - + Improved uniformity, telecentric illumination
 - + Very convenient – higher yield!
-
- + One optics set for both Contact and Proximity Lithography
 - + Advanced Mask Aligner Lithography (AMALITH)

ARE YOU STILL USING THE **CONVENTIONAL** MASK ALIGNER ILLUMINATION SYSTEM?

WE WOULD LIKE TO VISIT YOU TO SHOW YOU OUR NEW **SELF CALIBRATING** MO EXPOSURE OPTICS®!



"We love our MO Exposure Optics.
It's so convenient!"

ADVANCED MASK ALIGNER LITHOGRAPHY (AMALITH)

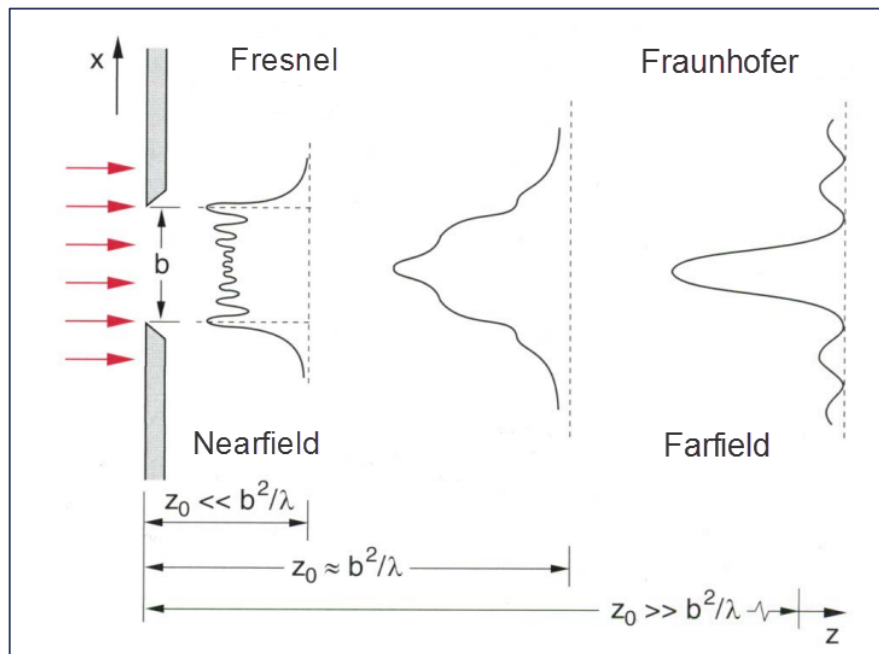
Pushing the limits!

- + Customized Illumination
 - Reduce diffraction effects (apodization)
- + Optical Proximity Correction (OPC)
 - Improve critical resist structures
- + Source Mask Optimization (SMO)
 - Customized Illumination and OPC
- + Alternating Aperture Phase Shift Mask (AAPSM)
- + ...



www.asml.com

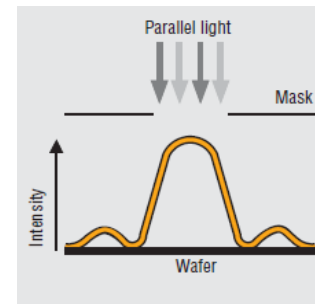
- + Diffraction effects
- + Proximity artifacts
- + Sidelobes



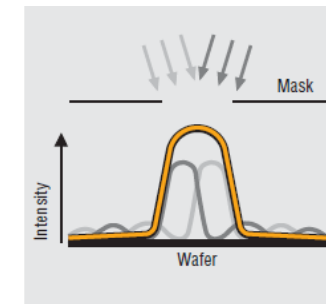
Parallel Light



Diffuse Light

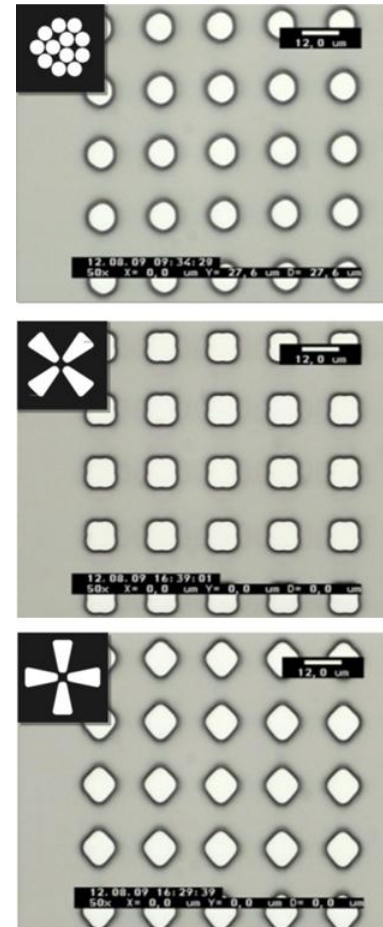
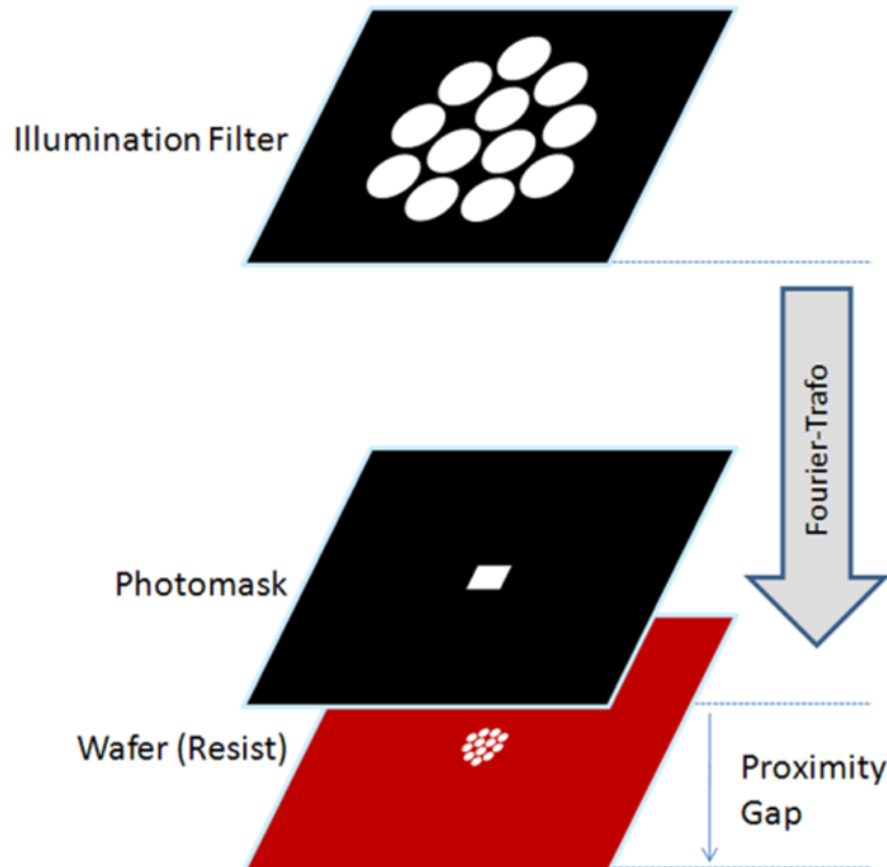


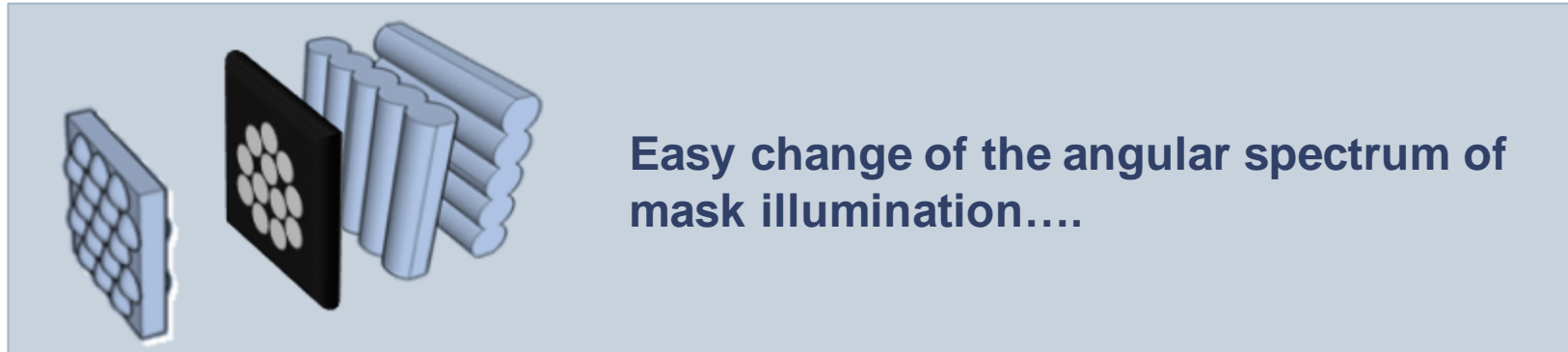
Parallel Light
(sidelobes)



Apodization

SHADOW PRINTING – CAMERA OBSCURA





SUSS HR Optics



Large Gap



SUSS D Optics



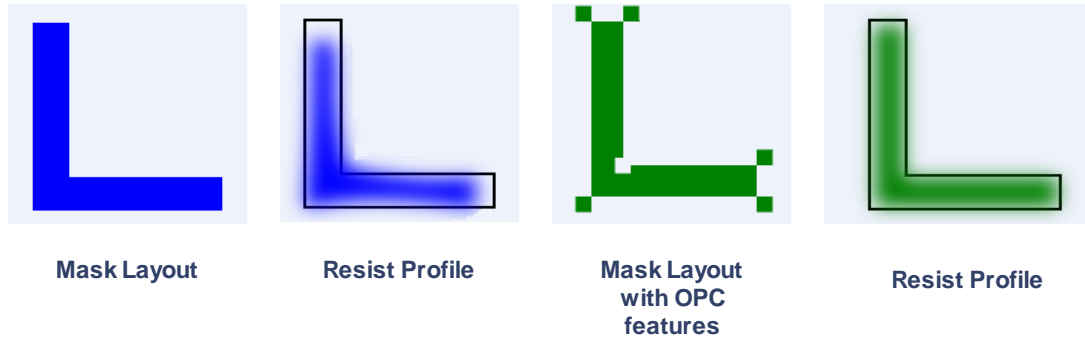
Quadrupole



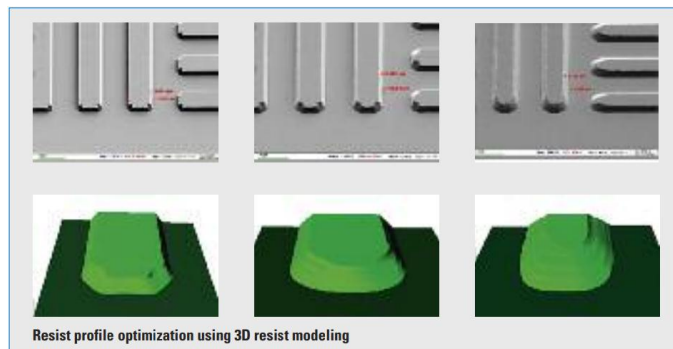
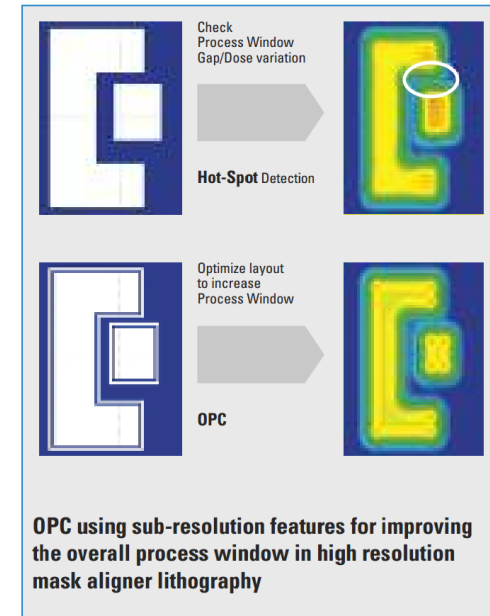
Ring



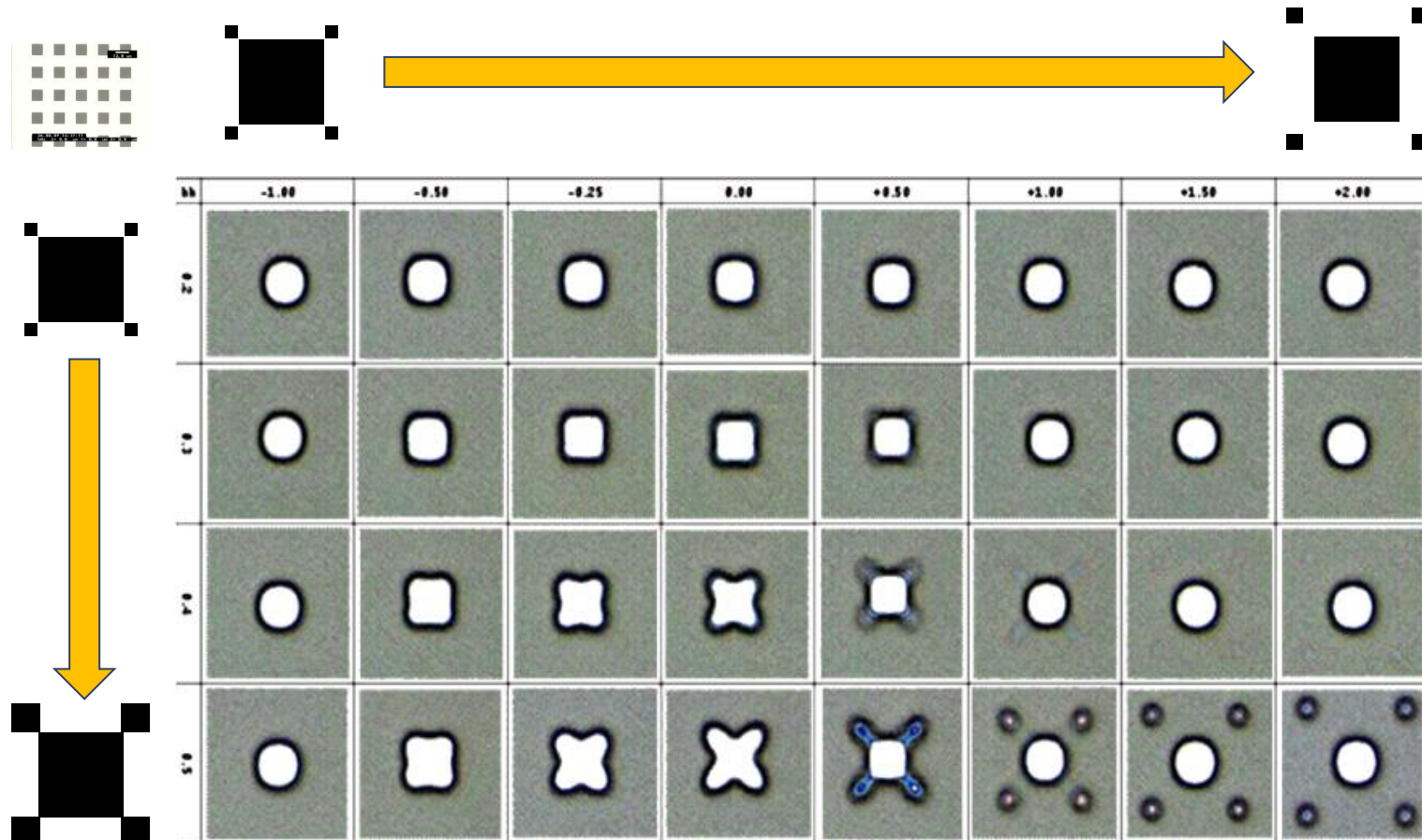
+ Optimization of the mask pattern (Optical Proximity Correction, OPC)



+ Full simulation of litho process by using LayoutLAB™ software from GenISys



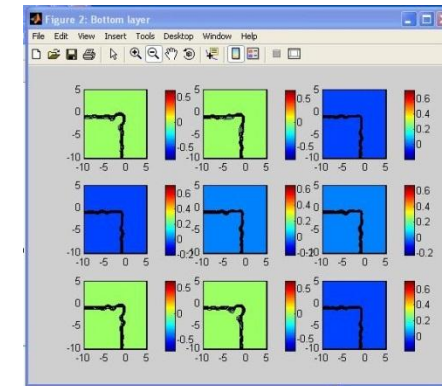
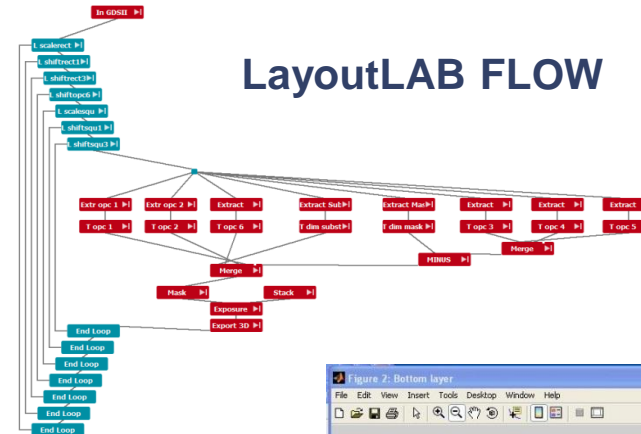
OPTICAL PROXIMITY CORRECTION (OPC)



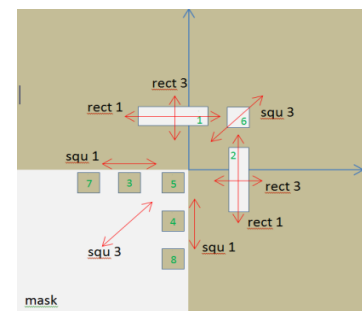
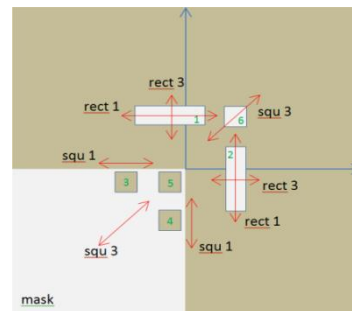
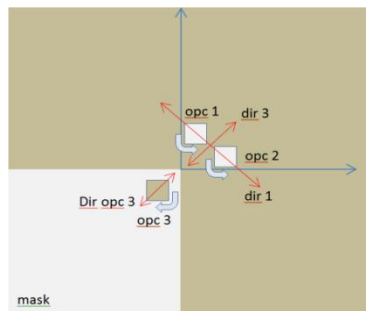
Square 10µm x 10µm, Proximity Gap 50µm, Photoresist AZ4110, 1.2µm thick

PROCEDURE

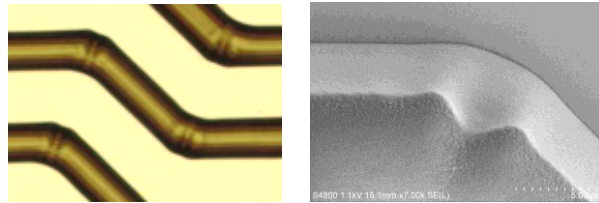
- + Iterative simulations of different OPC mask layers
- + Export of the aerial image for the different simulated settings (optimized for 30, 50 and 100 μm exposure gaps)
- + Matlab data elaboration
- + LayoutLAB resist (calibrated) simulation for the resulting best profiles



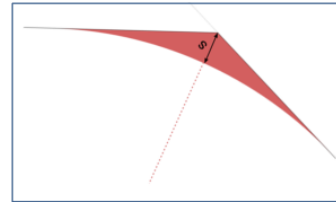
MASK LAYOUTS



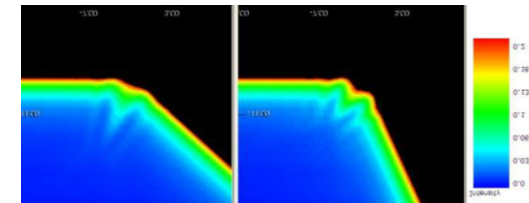
INDUSTRY EXAMPLE: REDUCTION OF PROXIMITY ARTIFACTS BY SMO



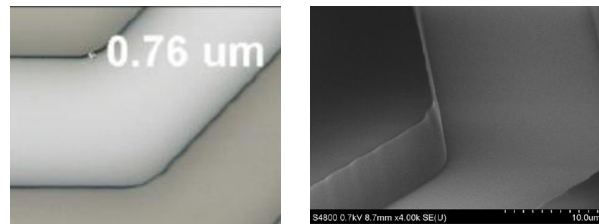
*Proximity artifacts in redistribution lanes:
Deformations in lane edges.*



Fillet reduces erosion

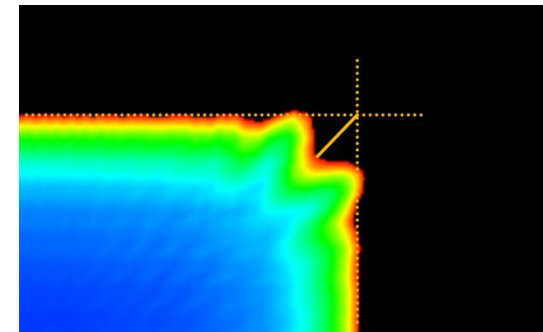


Simulation LayoutLAB software



*Corrected: 30μm Exp Gap, SB 90°C, 300sec, 650mJ
in MA200 Compact with MO Exposure Optics*

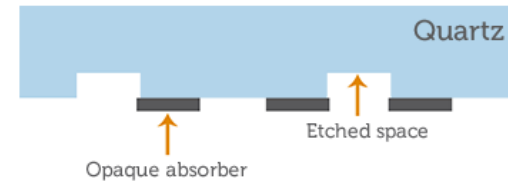
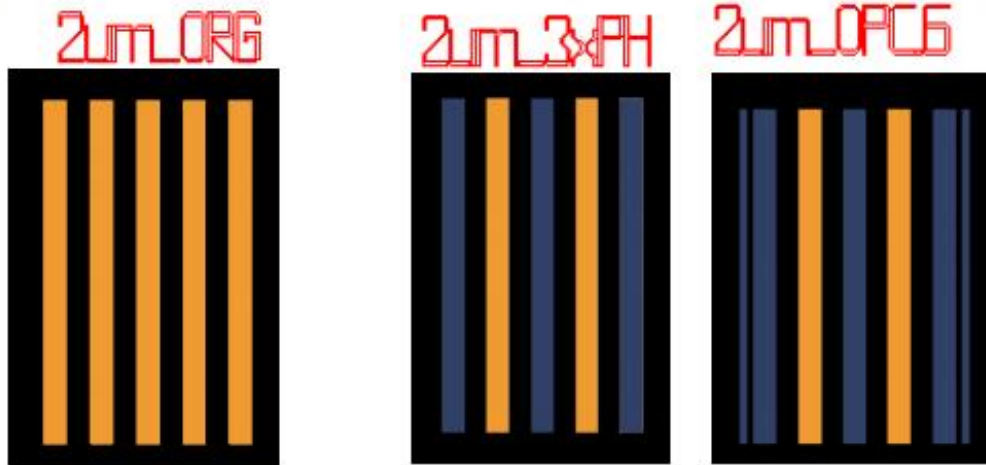
Source Mask Optimization (SMO)



*Proximity artifact: Deformation
(protrusion) due to diffraction effects
(simulation in LayoutLAB)*

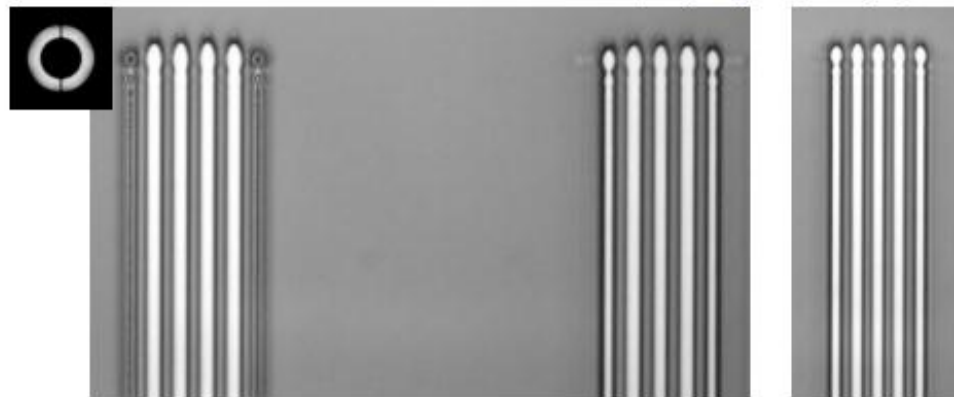
- + Simulation enables significant process improvements
- + Customer purchased five MA200 Compact Mask Aligners equipped with MO Exposure Optics®

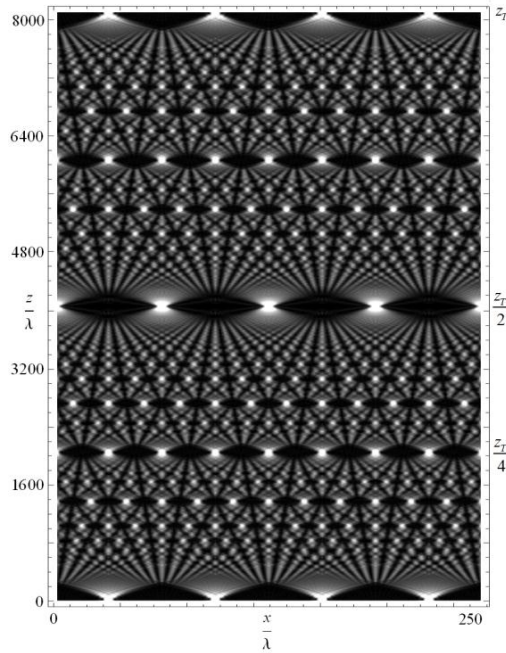
L&S 2 μm IN MASK ALIGNER AT 30 μm PROXIMITY GAP



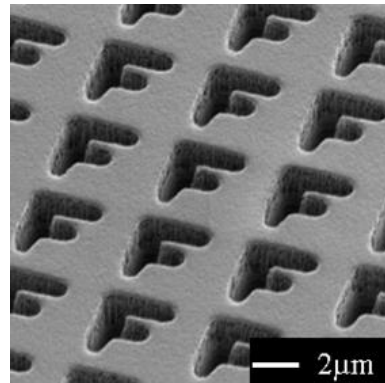
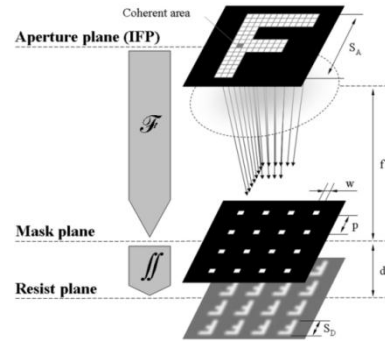
Alternating Aperture
Phase Shift Mask
(AAPSM)

Broadband, Big ring IFP, 12s [57]

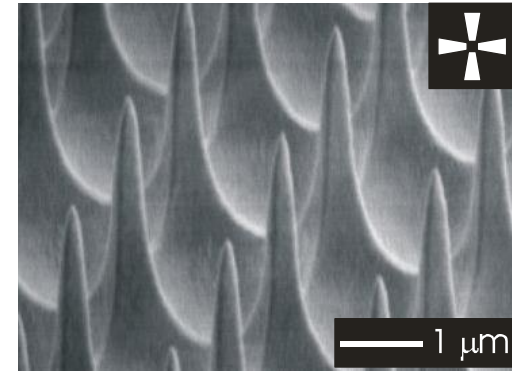




Talbot Lithography

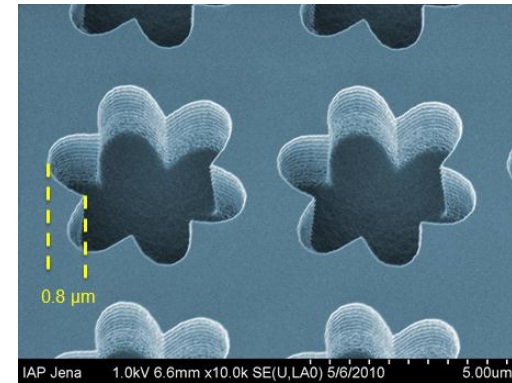


MO Pinhole-Talbot Lithography



MO Half-tone Proximity Lithography

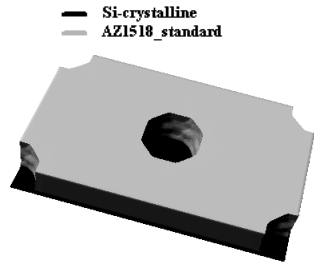
10 μm proximity gap



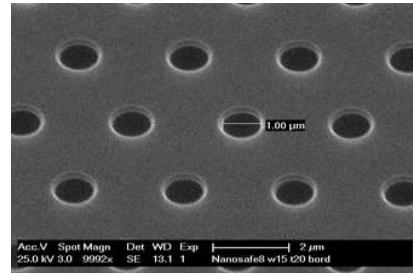
MO Pinhole-Talbot Lithography

102 μm proximity gap

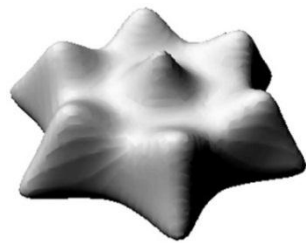
+ Contact printing of 1 μ m structures



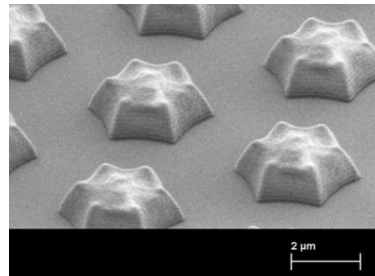
Simulation result



Printing result

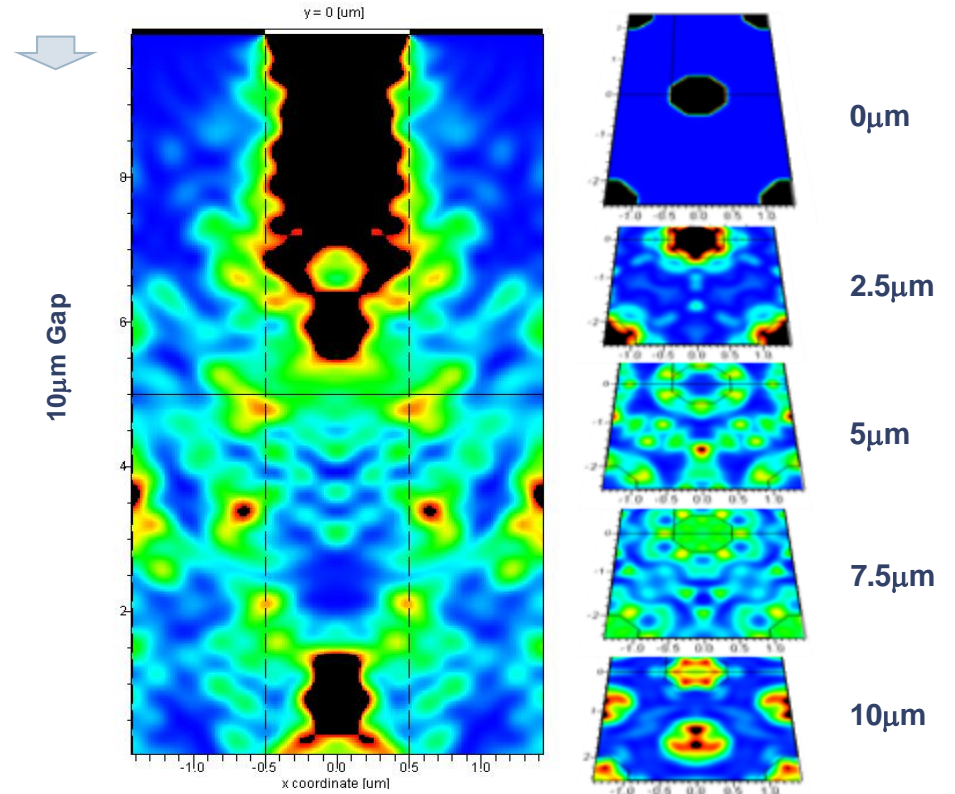


Simulation



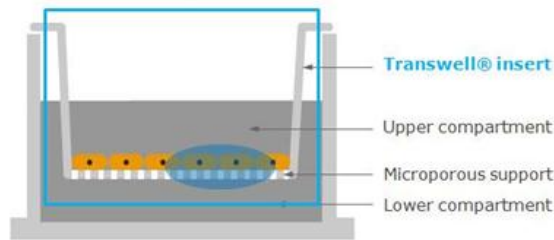
Print result

+ Simulations using LayoutLAB™

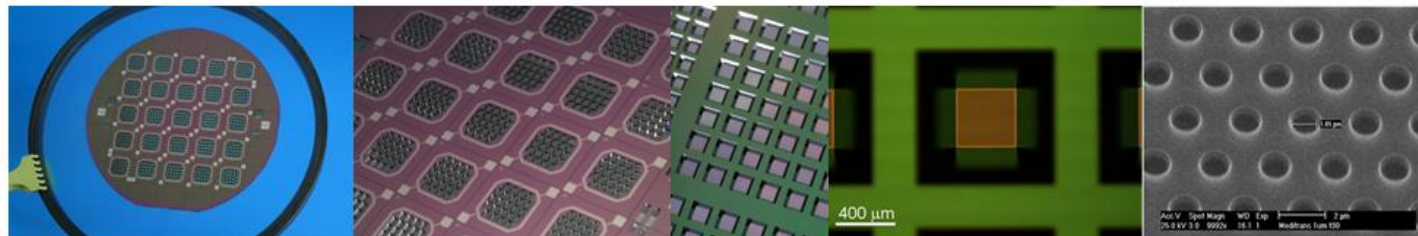
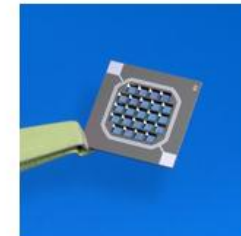


AMALITH for porous supports for cell cultures

- Microfabricated cell supports have unique features not found in commercially available versions
- *Need for low cost process for submicron pore dimensions*
- Strong interest from end-users in toxicology and pharmacology



Adapted from Corning technical information



Swiss KT/CTI Project "AMALITH"

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"We love our MO Exposure Optics.
It's so convenient!"

AVAILABLE FOR ALL SUSS MASK ALIGNERS



MA6, MA8



MJB4



LithoPack 300



MA/BA8 Gen3



*MA200Compact,
MA100e, MA150e*



MA300 Gen2





Thank you!

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